

## NCE30TD60BP

#### 600V, 30A, Trench FS II Fast IGBT

#### **General Description:**

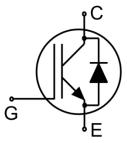
Using NCE's proprietary trench design and advanced FS (Field Stop) second generation technology, the 600V Trench FS II IGBT offers superior conduction and switching performances, and easy parallel operation;

#### **Features**

- Trench FSII Technology offering
- Very low V<sub>CE(sat)</sub>
- High speed switching
- Positive temperature coefficient in V<sub>CE(sat)</sub>
- Very tight parameter distribution
- High ruggedness, temperature stable behavior

#### **Application**

- Air Condition
- Inverters
- Motor drives



Schematic diagram

#### **Package Marking and Ordering Information**

Device	Device Package	Device Marking		
NCE30TD60BP	TO-3P	NCE30TD60BP		



## **Absolute Maximum Ratings (Tc=25°C unless otherwise noted)**

**TO-3P** 

Symbol	Parameter	Value	Units
Vces	Collector-Emitter Voltage	600	V
V <sub>GES</sub>	Gate- Emitter Voltage	±30	V
	Collector Current	60	Α
Ic	Collector Current @T <sub>C</sub> = 100°C	30	Α
I <sub>Cplus</sub>	Pulsed Collector Current, tp limited by T <sub>jmax</sub>	90	Α
-	turn off safe operating area, V <sub>CE</sub> =600V, Tj=150°C	90	Α
I <sub>F</sub>	Diode Continuous Forward Current @T <sub>C</sub> = 100°C	30	Α
I <sub>FM</sub>	Diode Maximum Forward Current	90	Α
	Power Dissipation @ T <sub>C</sub> = 25°C	190	W
P <sub>D</sub>	Power Dissipation @T <sub>C</sub> = 100 °C	95	W
T <sub>J</sub> ,T <sub>stg</sub>	Operating Junction and Storage Temperature Range	-55 to +175	°C
TL	Maximum Temperature for Soldering	260	°C
t <sub>sc</sub>	Short circuit withstand time V <sub>GE</sub> =15V, V <sub>CC</sub> ≤400V, Allowed number of short circuits<1000Time between short circuits:≥1.0s,T <sub>j</sub> ≤150°C	5	us



## NCE30TD60BP

**PbFreeProduct** 

#### **Thermal Characteristic**

Symbol	Parameter	Value	Units
Rejc	Thermal Resistance, Junction to case for IGBT	0.78	°C/W
R <sub>θ</sub> JC	Thermal Resistance, Junction to case for Diode	1.08	°C/W
ReJA	Thermal Resistance, Junction to Ambient	40	°C/W

## Electrical Characteristics (Tc=25°C unless otherwise noted)

Ol	Danamatan.	Test Conditions		Value			
Symbol	Parameter			Min.	Тур.	Max.	Units
Static Chara	cteristics						
V <sub>(BR)CES</sub>	Collector-Emitter Breakdown Voltage	V <sub>GE</sub> =0V	,I <sub>CE</sub> =1mA	600			V
Ices	Collector-Emitter Leakage Current	V <sub>GE</sub> =0V	Vce=600V			4	uA
I <sub>GES(F)</sub>	Gate to Emitter Forward Leakage	V <sub>GE</sub> =+30	V,V <sub>CE</sub> =0V			200	nA
I <sub>GES(R)</sub>	Gate to Source Reverse Leakage	V <sub>GE</sub> =-30	V,Vce =0V			200	nA
\/	Callegator Fraitter Catagories Valtage	Ic=30A	Tj=25°C		1.7	1.9	V
V <sub>CE(sat)</sub>	Collector-Emitter Saturation Voltage	V <sub>GE</sub> =15V	Tj=150°C		1.9		V
V <sub>GE(th)</sub>	Gate Threshold Voltage	Ic=1mA	,Vce=Vge	4.0	5.0	6.0	V
Dynamic Cha	aracteristics						
Cies	Input Capacitance	V <sub>CE</sub> =25V,V <sub>GE</sub> =0V, f=1MHz			3552		pF
Coes	Output Capacitance				106		
C <sub>res</sub>	Reverse Transfer Capacitance				67		
Qg	Total Gate Charge	Vcc=480V, Ic=30A VgE=15V			132		nC
Qge	Gate to Emitter Charge				28		
Qgc	Gate to Collector Charge				54		
I <sub>C(SC)</sub>	Short circuit collector current Max.1000 short circuits Time between short circuits: ≥1.0s	V <sub>GE</sub> =15V,V <sub>CC</sub> ≤400V, t <sub>SC</sub> ≤5us,Tj≤150°C			190		А
Switching Cl	naracteristics						
$t_{d(ON)}$	Turn-on Delay Time				19		
t <sub>r</sub>	Rise Time	Vcc=400V,Ic=30A			17		ns
t <sub>d(OFF)</sub>	Turn-Off Delay Time				166		
t <sub>f</sub>	Fall Time	V <sub>GE</sub> =0/15V, R <sub>g</sub> =5Ω			16		
Eon	Turn-On Switching Loss	Inductive Load			0.36		
E <sub>off</sub>	Turn-Off Switching Loss				0.32		mJ
Ets	Total Switching Loss	1			0.68		

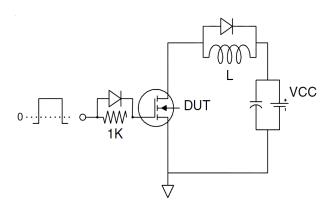
## Electrical Characteristics of the Diode (T<sub>C</sub>= 25°C unless otherwise specified):

Symbol	Darameter	Took Conditions	Rating			llm!ta
	Parameter	Test Conditions	Min.	Тур.	Max.	Units
V <sub>FM</sub>	Diode Forward Voltage	I <sub>F</sub> =30A	-	1.7	1.9	V
Trr	Reverse Recovery Time			178		ns
I <sub>RRM</sub>	Diode Peak Reverse Recovery Current	I <sub>F</sub> =30A, di/dt=200A/us		4		Α
Qrr	Reverse Recovery Charge			0.4		uC
Pulse width t <sub>tp</sub> ≤380μs,δ≤2%						

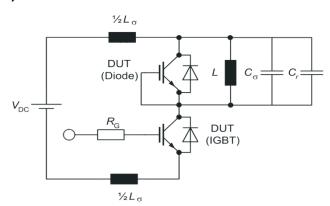


#### **Test Circuit**

#### 1) Gate Charge Test Circuit

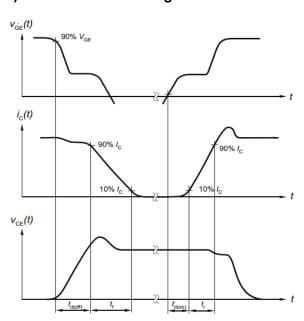


#### 2) Switch Time Test Circuit

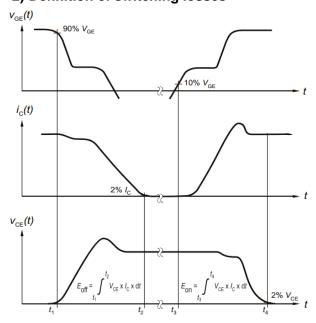


#### **Switching characteristics**

#### 1) Definition of switching times

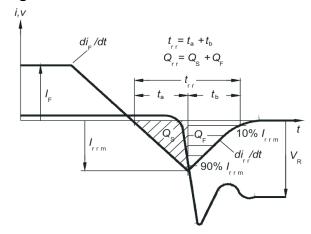


#### 2) Definition of switching losses



#### 3) Definition of diode switching characteristics

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#### **Typical Electrical and Thermal Characteristics**

#### **Figure 1 Output Characteristics**

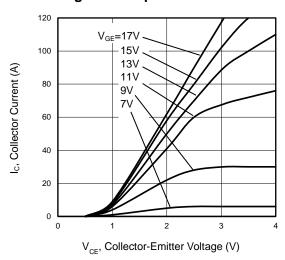
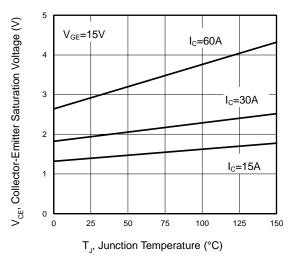
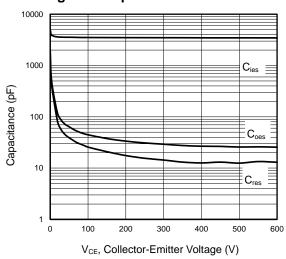


Figure 3 V<sub>CEsat</sub> vs. Case Temperature



**Figure 5 Capacitance Characteristics** 



**Figure 2 Transfer Characteristics** 

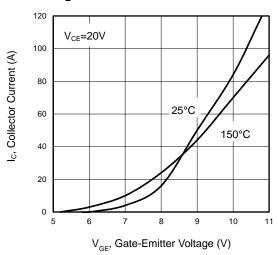


Figure 4 Saturation Voltage vs. V<sub>GE</sub>

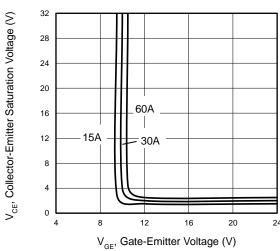
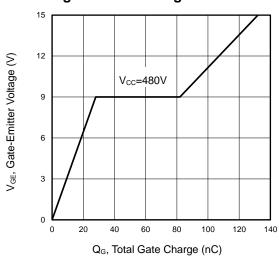


Figure 6 Gate charge waveform





#### **Typical Electrical and Thermal Characteristics**

# Figure 7 Gate-emitter Threshold Voltage as a Function of Junction Temperature

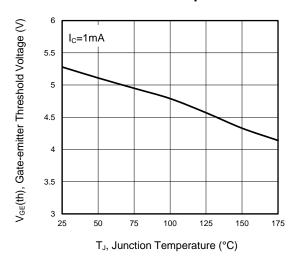


Figure 9 Typical Switching Times as a Function of Gate Resistor

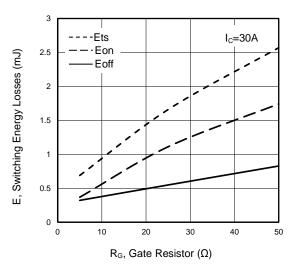


Figure 11 Typical Collector-emitter Saturation
Voltage as a function of Collector Current

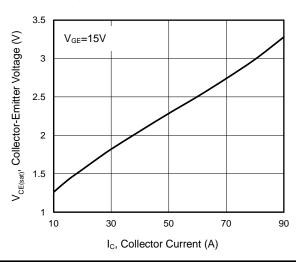


Figure 8 Power Dissipation as a Function of Case Temperature

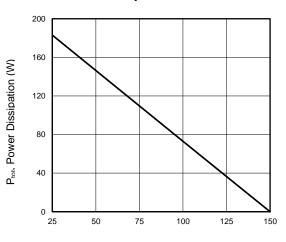
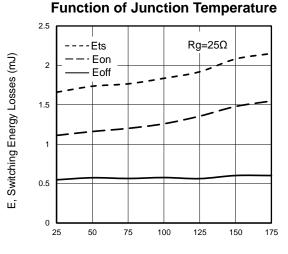


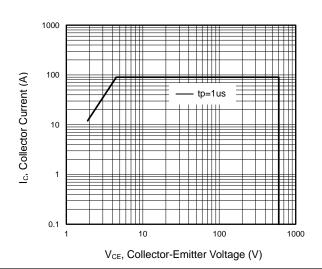
Figure 10 Typical Switching Times as a

T<sub>C</sub>, Case Temperature (°C)



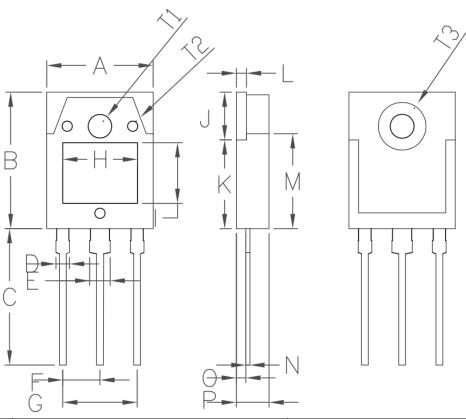
T<sub>J</sub>, Junction Temperature (°C)

Figure 13 Forward Bias Safe Operating Area





# **TO-3P-3L Package Information**



O	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	15.50	15.70	0.61	0.62	
В	19.70	20.10	0.78	0.79	
С	20.10	20.50	0.79	0.81	
D	2.0	00	0.	08	
E	3.0	00	0.	12	
F	5.4	45	0.	21	
G	10.	10.90		43	
Н	10.80	11.00	0.43	0.43	
I	8.80	9.00	0.35	0.35	
J	6.85	7.15	0.27	0.28	
K	12.75	13.05	0.50	0.51	
L	1.49	1.51	0.06	0.06	
М	13.70	14.00	0.54	0.55	
N	0.59	0.61	0.02	0.02	
0	1.32	1.48	0.05	0.06	
Р	4.70	4.90	0.19	0.19	
T1	3.9	50	0.14		
T2	1.9	50	0.06		
Т3	7.00		0.28		

## NCE30TD60BP

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